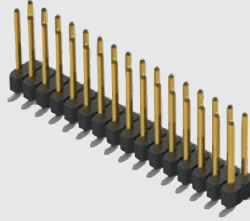
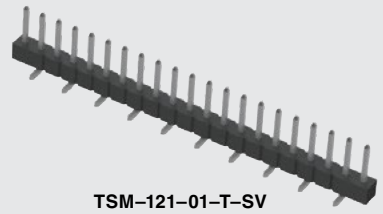




TSM-116-02-S-DV-LC



TSM-121-01-T-SV



(2.54 mm) .100"

SMT .025" SQ POST HEADER

Board Mates:

SSW, SSQ, SSM, BSW, ESW, ESQ, BCS, SLW, CES, HLE

Cable Mates:

IDSS, IDSD

SPECIFICATIONS

For complete specifications and recommended PCB layouts see www.samtec.com?TSM

Insulator Material:

Black Liquid Crystal Polymer

Terminal Material:

Phosphor Bronze

Plating:

Au or Sn over 50 μm (1.27 μm) Ni

Operating Temp Range:

-55 °C to +105 °C with Tin;

-55 °C to +125 °C with Gold

Voltage Rating:

475 VAC -SV/-DV mated with BCS or SSM

RoHS Compliant: Yes

RoHS Compliant: Yes

MATES	CURRENT RATING (PER PIN)
TSM/SSW	4.7 A
TSM/SSM	5.4 A
TSM/HLE	4.1 A
2 PINS POWERED	

PROCESSING

Lead-Free Solderable: Yes

-DH/-SH Lead Coplanarity: (0.15 mm) .006" max (02-36)*

-DV/-SV Lead Coplanarity: (0.10 mm) .004" max (02-05)

(0.13 mm) .005" max (06-10)*

(0.15 mm) .006" max (11-36)*

*(.004" stencil solution may be available; contact IPG@samtec.com)

RECOGNITIONS

For complete scope of recognitions see www.samtec.com/quality

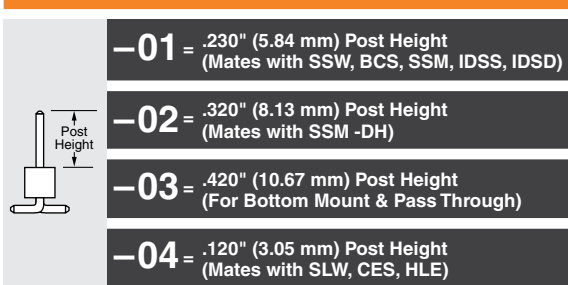


ALSO AVAILABLE (MOQ Required)

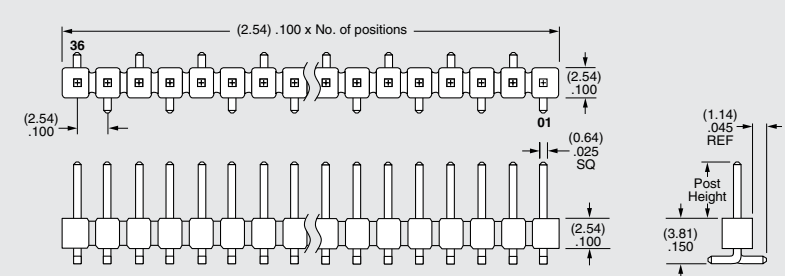
- Edge Mount and Locking Clips for -SV
- Solder Locks for -DH and Shrouds for -DV
- Other platings

Note: Some lengths, styles and options are non-standard, non-returnable.

TSM	1	NO. PINS PER ROW	LEAD STYLE	PLATING OPTION	ROW OPTION
		02 thru 36		-F = Gold flash on post, Matte Tin on tail	
				-L = 10 μm (0.25 μm) Gold on post, Matte Tin on tail	
				-S = 30 μm (0.76 μm) Gold on post, Matte Tin on tail	
				-T = Matte Tin	

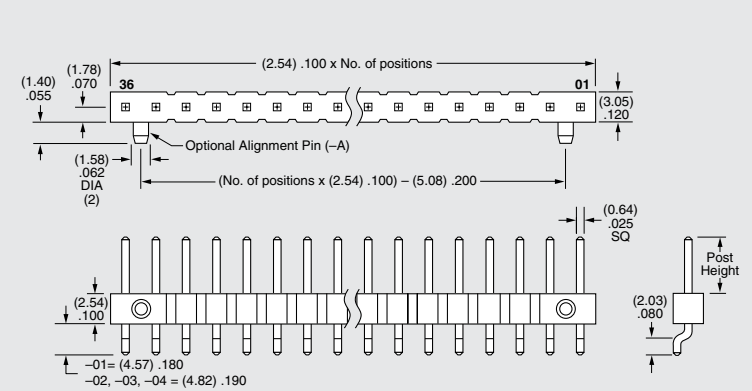


-SV = Single Row Vertical Pin



APPLICATIONS

-SH = Single Row Horizontal Pin



Due to technical progress, all designs, specifications and components are subject to change without notice.

